

## Amendments to the Claims

1 (original) A method for manufacturing a fluorocarbon film characterized by including a step (SA1) for introducing a mixed gas comprising a first carbon fluoride gas and a second carbon fluoride gas on a substrate placed inside a chamber, and depositing a fluorocarbon film on said substrate; and a step (SA2) for forming voids in said fluorocarbon film by selectively removing volatile components contained in said fluorocarbon film.

2 (original) A method for manufacturing a fluorocarbon film, characterized by including a step (SA1) for introducing a mixed gas comprising a first carbon fluoride gas and a second carbon fluoride gas on a substrate placed inside a chamber, and depositing a fluorocarbon film on said substrate; and a step (SA2) for forming voids in said fluorocarbon film by selectively removing volatile components contained in said fluorocarbon film; wherein

said first carbon fluoride gas is a fluorine-containing compound having 4 to 5 carbon atoms; and said second carbon fluoride gas is a fluorine-containing compound having 6 to 12 carbon atoms.

3 (currently amended) The method for manufacturing a fluorocarbon film according to claim 2, ~~characterized in that~~ wherein said first carbon fluoride gas is octafluorocyclopentene.

4 (currently amended) The method for manufacturing a fluorocarbon film according to claim 2, ~~characterized in that~~ wherein said second carbon fluoride gas is hexafluorobenzene.

5 (currently amended) The method for manufacturing a fluorocarbon film according to claim 1 ~~or 2, characterized in that~~ wherein said step (SA2) for forming voids includes a step for cleaning said fluorocarbon film with a supercritical fluid.

6 (currently amended) The method for manufacturing a fluorocarbon film according to claim 1 ~~or 2, characterized in that~~ wherein said step (SA2) for forming voids includes a step for heating said fluorocarbon film.

7 (currently amended) The method for manufacturing a fluorocarbon film according to claim 1 ~~or 2, characterized in that~~ wherein said chamber is a plasma exciting chamber that can internally generate plasma.

8 (currently amended) The method for manufacturing a fluorocarbon film according to claim 1 ~~or 2, characterized in that~~ wherein said first carbon fluoride gas has relatively high volatility and said second carbon fluoride gas has relatively low volatility.

9 (currently amended) A fluorocarbon film ~~characterized in that~~ wherein a large number of fine voids are internally formed, and specific inductive capacity is within a range of 2 or less.

10 (original) A surface-coating material for a printed substrate for high-frequency circuits composed of the fluorocarbon film according to claim 9.

11 (original) A gas adsorbing material that contains the fluorocarbon film according to claim 9.

12(original) An electronic device that uses the fluorocarbon film according to claim 9 in at least a part.

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